

**VIA FORMATION IN POLYMERS****Abstract of the Disclosure**

A method for forming relatively small vias in polymers which may have an underlying layer is disclosed. In a first embodiment, plated pillars are formed on a plated bottom metal layer. A polymer is coated over the first metal layer and the plated pillars and cured. The polymer is blanket etched to expose the top surface of the plated pillars. A metal layer is formed on top of the polymer layer and exposed surfaces of the plated pillars. In a second embodiment of the invention, pillars made from a photoresist are formed over a bottom metal layer. A polymer layer is coated over the pillars and the bottom metal layer and blanket etched to the surface of the photoresist pillar. The photoresist pillars are then removed forming vias. A top metal layer is formed on top of the polymer coating in the vias to connect to the bottom metal layer.